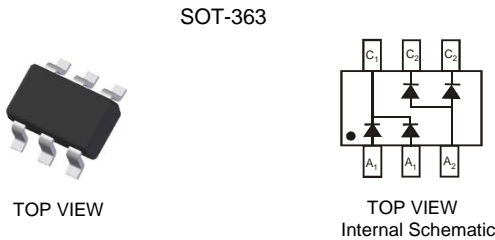


Features

- Fast Switching Speed
- Small Surface Mount Package
- For General Purpose Switching Applications
- One BAV70 Circuit and One BAW56 Circuit In One Package
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen- and Antimony-Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at <https://www.diodes.com/products/automotive/automotive-products/>.**
- **This part is qualified to JEDEC standards (as references in AEC-Q) for High-Reliability. <https://www.diodes.com/quality/product-definitions/>**

Mechanical Data

- Case: SOT-363
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Matte Tin Finish Annealed over Alloy 42 Lead-Frame, Solderable per MIL-STD-202, Method 208 ③
- Polarity: See Diagram
- Weight: 0.006 grams (Approximate)

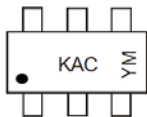


Ordering Information (Note 4)

| Part Number | Qualification | Case | Packaging |
|--------------|---------------|---------|------------------|
| BAW567DW-7-F | Commercial | SOT-363 | 3000/Tape & Reel |

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



KAC = Product Type Marking Code
 YM = Date Code Marking
 Y = Year ex: H = 2020
 M = Month ex: 9 = September

Date Code Key

| Year | 2015 | 2016 | 2017 | 2018 | 2019 | 2020 | 2021 | 2022 | 2023 | 2024 | 2025 | 2026 |
|------|------|------|------|------|------|------|------|------|------|------|------|------|
| Code | C | D | E | F | G | H | I | J | K | L | M | N |

| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | O | N | D |

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

| Characteristic | Symbol | Value | Unit |
|---|--------------|-------|------|
| Non-Repetitive Peak Reverse Voltage | V_{RM} | 100 | V |
| Peak Repetitive Reverse Voltage | V_{RRM} | 75 | V |
| Working Peak Reverse Voltage | V_{RWM} | | |
| DC Blocking Voltage | V_R | | |
| RMS Reverse Voltage | $V_{R(RMS)}$ | 53 | V |
| Forward Continuous Current (Note 5) | I_{FM} | 300 | mA |
| Average Rectified Output Current (Note 5) | I_O | 150 | mA |
| Non-Repetitive Peak Forward Surge Current @ $t = 2.0\mu\text{s}$ (Note 6) | I_{FSM} | 2.0 | A |
| @ $t = 1.0\text{s}$ | | 1.0 | |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|---|-----------------|-------------|--------------------|
| Power Dissipation (Note 5) | P_D | 200 | mW |
| Thermal Resistance Junction to Ambient Air (Note 5) | $R_{\theta JA}$ | 625 | $^\circ\text{C/W}$ |
| Operating and Storage Temperature Range | T_J, T_{STG} | -55 to +150 | $^\circ\text{C}$ |

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

| Characteristic | Symbol | Min | Max | Unit | Test Condition |
|------------------------------------|-------------|-----|-------------------------------|---|--|
| Reverse Breakdown Voltage (Note 7) | $V_{(BR)R}$ | 75 | — | V | $I_R = 2.5\mu\text{A}$ |
| Forward Voltage | V_F | — | 0.715 0.855 1.0 1.25 | V | $I_F = 1.0\text{mA}$ $I_F = 10\text{mA}$ $I_F = 50\text{mA}$ $I_F = 150\text{mA}$ |
| Reverse Current (Note 7) | I_R | — | 2.5 50 30 25 | μA μA μA nA | $V_R = 75\text{V}$ $V_R = 75\text{V}, T_J = 150^\circ\text{C}$ $V_R = 25\text{V}, T_J = 150^\circ\text{C}$ $V_R = 20\text{V}$ |
| Total Capacitance | C_T | — | 2.0 | pF | $V_R = 0, f = 1.0\text{MHz}$ |
| Reverse Recovery Time | t_{rr} | — | 4.0 | ns | $I_F = I_R = 10\text{mA}$, $I_{rr} = 0.1 \times I_R, R_L = 100\Omega$ |

- Notes:
5. Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
 6. Double Diode Loaded in parallel.
 7. Short duration pulse test used to minimize self-heating effect.

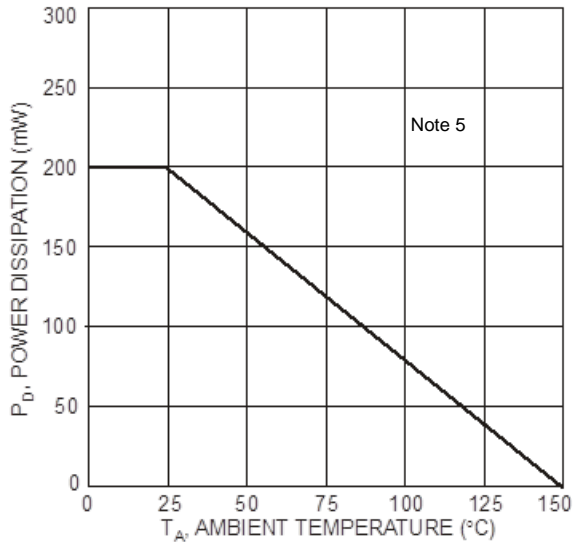


Fig. 1 Power Derating Curve, Total Package

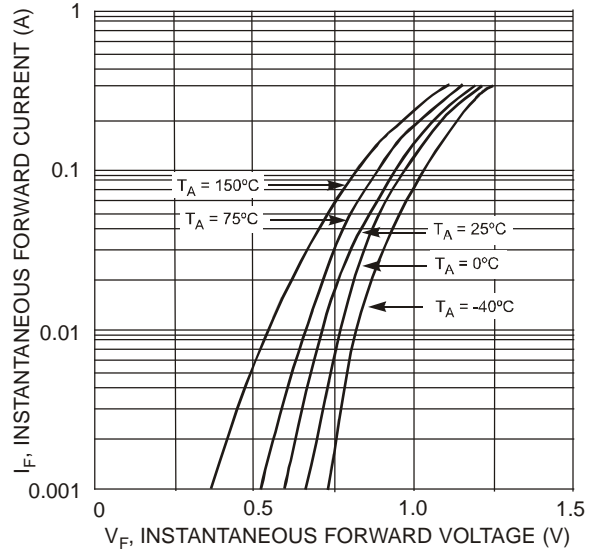


Fig. 2 Typical Forward Characteristics, Per Element

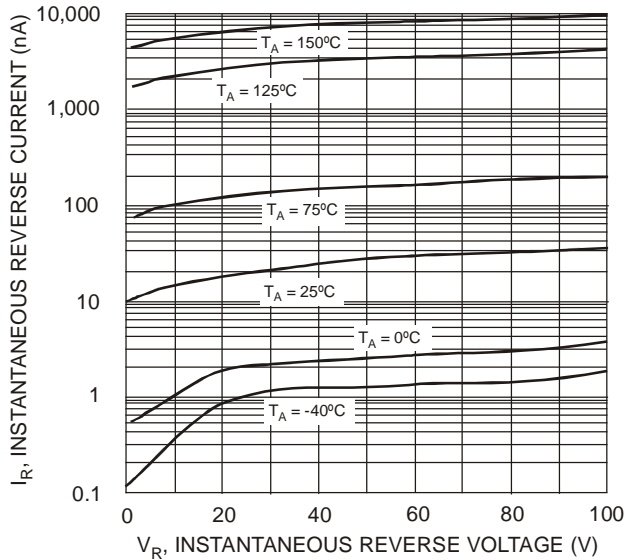


Fig. 3 Typical Reverse Characteristics, Per Element

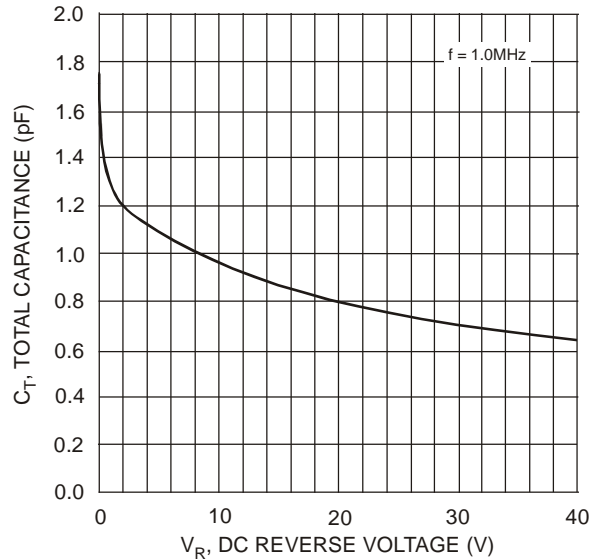
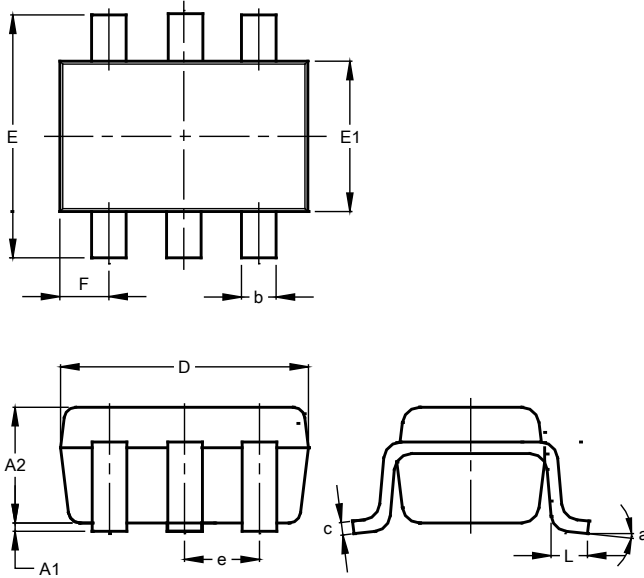


Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

Package Outline Dimensions

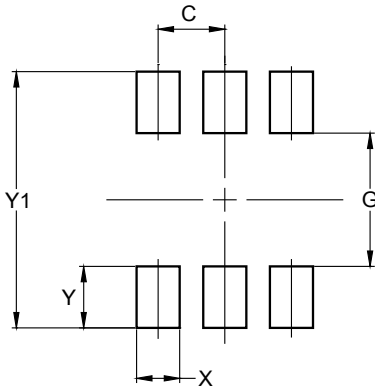
Please see <http://www.diodes.com/package-outlines.html> for the latest version.



| SOT363 | | | |
|-----------------------------|-----------|------|-------|
| Dim | Min | Max | Typ |
| A1 | 0.00 | 0.10 | 0.05 |
| A2 | 0.90 | 1.00 | 0.95 |
| b | 0.10 | 0.30 | 0.25 |
| c | 0.10 | 0.22 | 0.11 |
| D | 1.80 | 2.20 | 2.15 |
| E | 2.00 | 2.20 | 2.10 |
| E1 | 1.15 | 1.35 | 1.30 |
| e | 0.650 BSC | | |
| F | 0.40 | 0.45 | 0.425 |
| L | 0.25 | 0.40 | 0.30 |
| a | 0° | 8° | -- |
| All Dimensions in mm | | | |

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| C | 0.650 |
| G | 1.300 |
| X | 0.420 |
| Y | 0.600 |
| Y1 | 2.500 |

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